

Electronic Patent Application Fee Transmittal**Application Number:** 10537509**Filing Date:** 30-Nov-2005**Title of Invention:** Method for cutting semiconductor substrate**First Named Inventor/Applicant Name:** Fumitsugu Fukuyo**Filer:** Joseph John Buczynski/Towanna Bolling**Attorney Docket Number:** 46884-5388 (211285)

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees**Description****Fee Code****Quantity****Amount****Sub-Total in
USD(\$)****Basic Filing:****Pages:****Claims:****Miscellaneous-Filing:****Petition:****Patent-Appeals-and-Interference:****Post-Allowance-and-Post-Issuance:****Extension-of-Time:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180